	Material Compo © Copyright 2005. II international and Pan	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declara he declaration	tion of encom	the substances the substances and substances all lower	s within the er level mate	manufactur erials for wh	er listed ite hich the m	em. Note: i anufacturer	f the item is an as r has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	als and Mf	g Informati	ion		
Supplier	r Information														
Company name* Company				any unique ID			Unique ID Authority					Response Date*			
nsemi												2024-05-06			
Contact N	lame		Title - Contact				Phone - Contact*					Email - Contact*			
Product-H	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
roduct-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Iten		Number Mfr Item Name				Effective Dat	e Ve	ersion	sion Manufacturing Site		v	Veight*	UOM	Unit Type
		MURHF860CTG REC T0220FF		REC T0220FP 8A	600V ULTFS 2		2024-05-06			KR8		1	436.68	mg	Each
Ianufa	cturing Proccess Informat	tion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperatu		ure Max Time at Peak Tempera		Temperatu	ire Numb	per of Reflow Cyc	les		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		<b>30</b> sec		second	ls 3					
omments															
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) and				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.32	mg	Supplier	Silicon (Si)	7440-21-3		8.32	mg
Die Attach	13.08	mg	А	Lead (Pb)	7439-92-1	7a	12.426	mg
			Supplier	Tin (Sn)	7440-31-5		0.654	mg
Lead Frame	498.3	mg	Supplier	Copper (Cu)	7440-50-8		498.3	mg
Mold Compound-Black	897.4	mg		Phenolic Resin	proprietary data		44.87	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		67.305	mg
			Supplier	Carbon Black (C)	1333-86-4		4.487	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		197.428	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		583.31	mg
Plating	12.24	mg	Supplier	Tin (Sn)	7440-31-5		12.24	mg
Wire Bond - Al	7.34	mg	Supplier	Aluminum (Al)	7429-90-5		7.34	mg